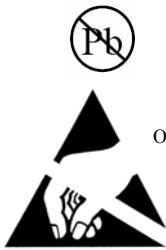


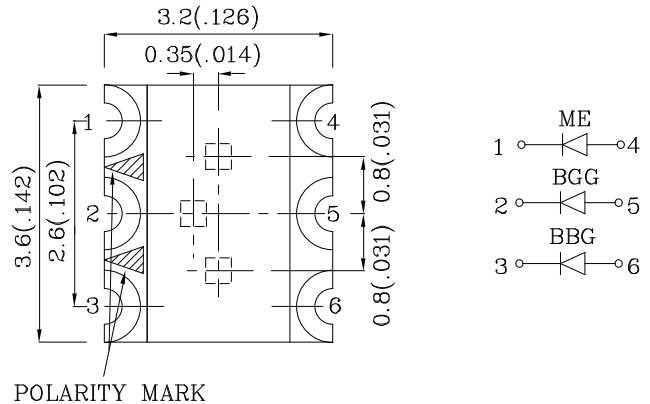
PRELIMINARY SPEC

Features

- LOW POWER CONSUMPTION.
- 3.2mmx3.6mm SMT LED, 1.1mm THICKNESS.
- CAN PRODUCE ANY COLOR IN VISIBLE SPECTRUM, INCLUDING WHITE LIGHT.
- ONE ORANGE, ONE GREEN AND ONE BLUE CHIPS IN ONE PACKAGE.
- PACKAGE : 1000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



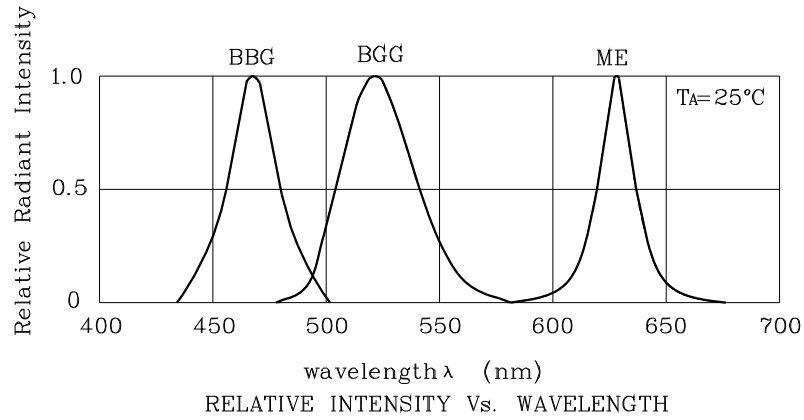
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ " unless otherwise noted.
3. Specifications are subject to change without notice.

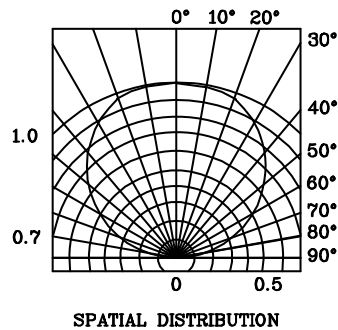
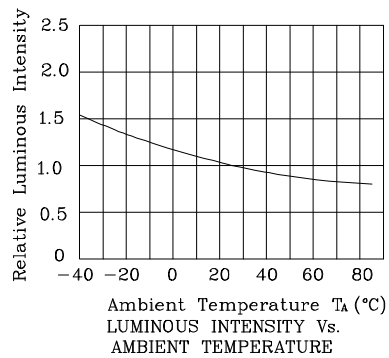
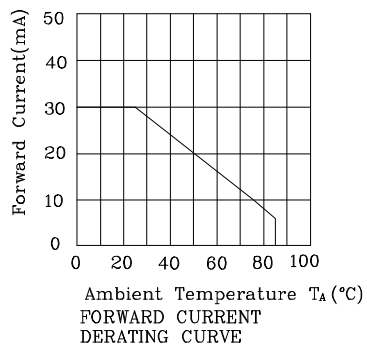
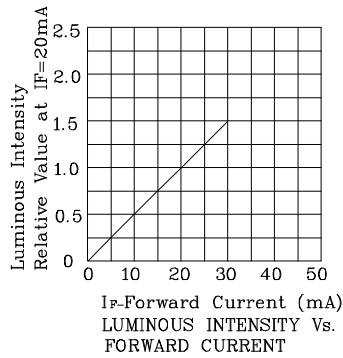
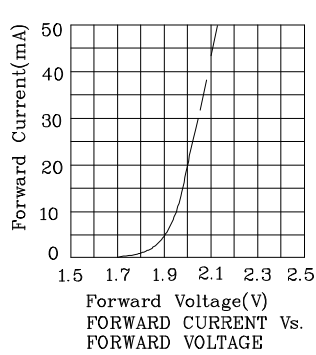
Absolute maximum ratings (TA=25°C)		ME (InGa AlP)	BGG (InGa N)	BBG (InG aN)	Unit
Reverse Voltage	V _R	5	5	5	V
Forward Current	I _F	30	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	195	100	100	mA
Power Dissipation	P _T	75	120	120	mW
Electrostatic Discharge Threshold (HBM)		-	1000	1000	V
Operating Temperature	T _A	-40 ~ +85			°C
Storage Temperature	T _{stg}	-40 ~ +85			

Operating Characteristics (TA=25°C)		ME (InGaA IP)	BGG (InGa N)	BBG (InG aN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	2.0	3.2	3.2	V
Forward Voltage (Max.) (I _F =20mA)	V _F	2.5	4.0	4.0	V
Reverse Current (Max.) (V _R =5V)	I _R	10	10	10	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λ _p	630	520	468	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λ _D	621	525	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	20	35	21	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	25	100	100	pF

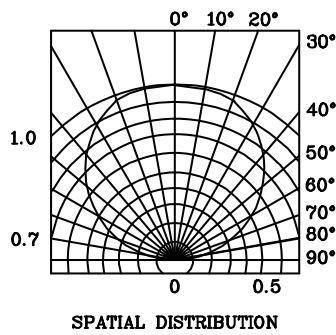
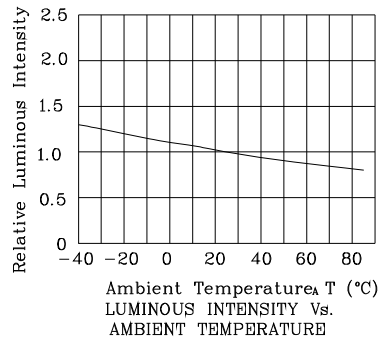
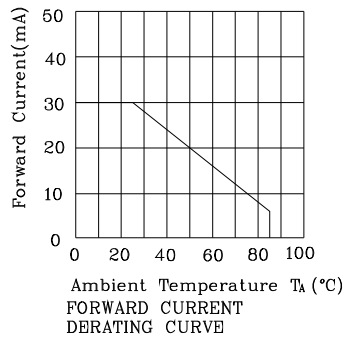
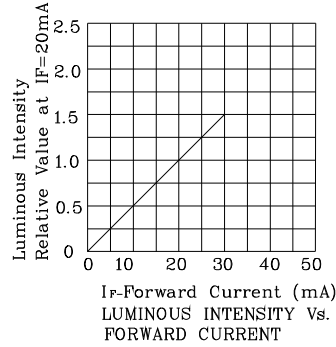
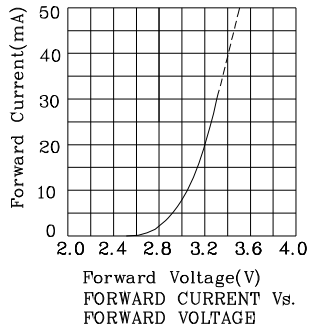
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ _P	Viewing Angle 2θ 1/2
				min.	typ.		
XZMEBGGBBG61W	Red	InGaAlP	Water Clear	110	297	630	120°
	Green	InGaN		110	248	520	
	Blue	InGaN		50	148	468	



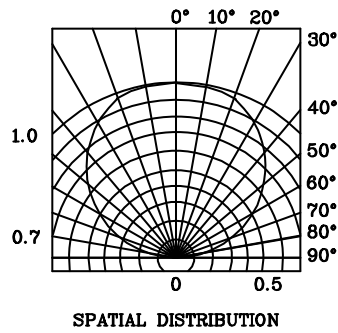
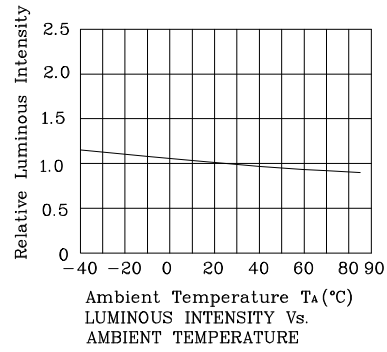
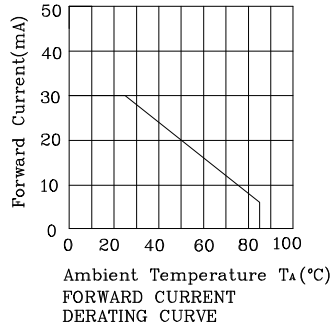
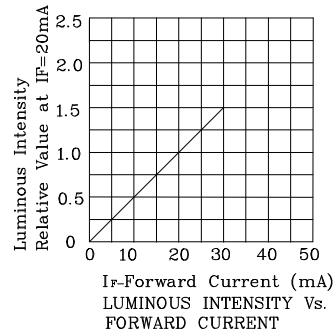
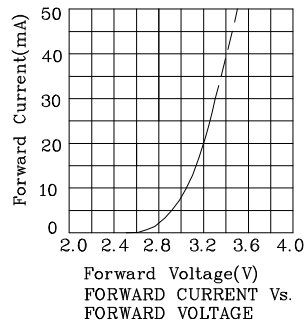
❖ ME



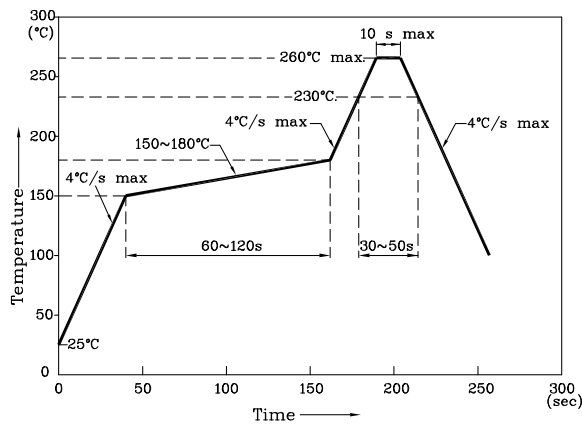
❖ BGG



❖ **BBG**



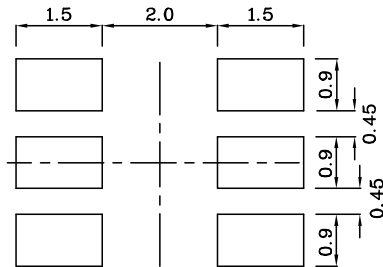
Reflow Soldering Profile For Lead-free SMT Process.



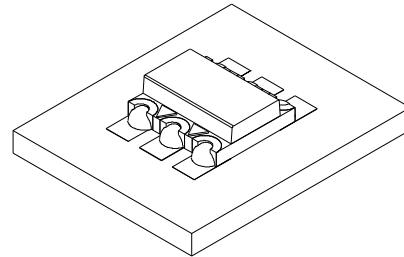
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C–260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

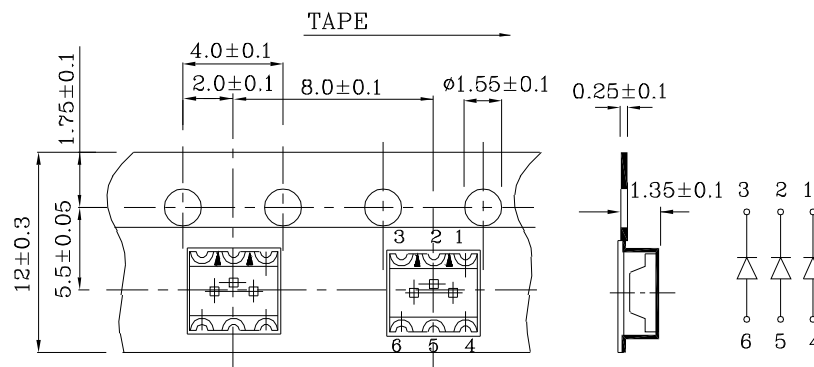
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

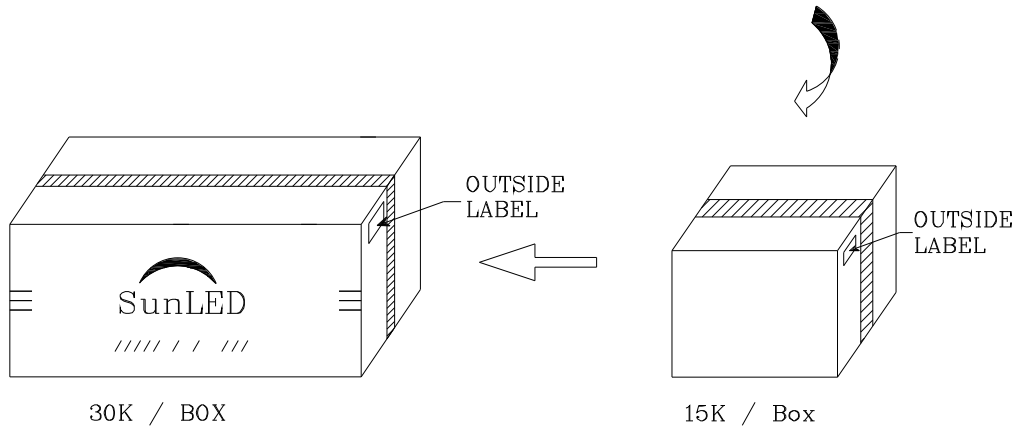
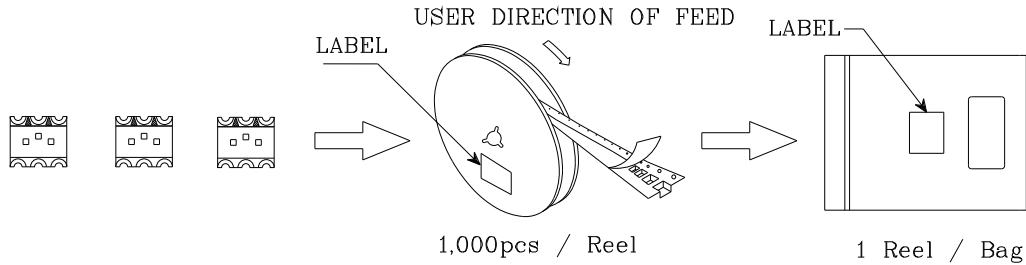

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity/ luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

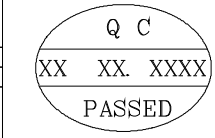

1. Wavelength: +/-1nm
2. Luminous intensity/ Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZMEBGGBBG61W

	
P/NO : XZxx61x	
QTY : 1,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	